

REV	ECR#	DESCRIPTION	DRAWN/DATE	CHECKED/DATE	APPROVED/DATE
A0	~	NEW DESIGN	Jason_thb 2014/11/25		JY.W 2014/11/25

NOTES :

1.0. RATING :

- 1.1. VOITAGE :60 VAC (R.M.S.)
- 1.2. NOMINAL CHARACTERISTIC IMPEDANCE: 50 Ohm
- 1.3. APPLICABLE FREQUENCY: DC ~ 6GHz
- 1.4. VSWR: 1.3 MAX. (DC~3GHz), 1.5 MAX. (3~6GHz)
- 1.5. TEMPERATURE : -40°C TO +85°C
- 1.6. APPLIED TO IR SOLDERING PROCESS

2.0. MATERIAL SEE BILL OF MATERIAL :

- 2.1.HOUSING: THERMOPLASTIC,UL94V-0,
- 2.2.CENTER CONTACT : COPPER ALLOY.
- 2.3.SHELL CONTACT: COPPER ALLOY.

3.0.PRODUCT NUMBERING CODE :

MRFB01 - B 0 1 1 0 0
 ① ② ③ ④ ⑤ ⑥ ⑦

① SERIES :

MRFB01 :MICRO RF I BAORD SMT CONNECTOR

② COLOR OF HOUSING :

B :HOUSING BLACK
 N :HOUSING NATURAL

③ MATERIAL OF HOUSING

0 :LCP

④ CONTACT OF PLATING :

- 1 :CENTER CONTACT 1u" ON CONTACT AREA,GOLD FLASH OTHER AREA;50u" MIN. NICKEL UNDERPLATING
- 2 :CENTER CONTACT 1.5u" ON CONTACT AREA,GOLD FLASH OTHER AREA;50u" MIN. NICKEL UNDERPLATING

⑤ GROUNDED OF PLATING :

- 1 :SHELL CONTACT 1u" ON CONTACT AREA,GOLD FLASH OTHER AREA;50u" MIN. NICKEL UNDERPLATING
- 2 :SHELL CONTACT 1.5u" ON CONTACT AREA,GOLD FLASH OTHER AREA;50u" MIN. NICKEL UNDERPLATING

⑥ OTHER :

0 :ALTERNATE

⑦ OTHER :

0 :ALTERNATE

CONTROL POINT FAI : to CRITICAL (Cpk & Cp) : DX = Places MAJOR (QC CHECKED) : ▼ = Places TOOL DESIGN DIMENSION : [T DIM] = Places EVALUATE REPORTS NUMBER	TOLERANCES UNLESS OTHERWISE SPECIFIED GENERAL X ±0.30 XX ±0.25 XXX ±0.15 ANGLES X ±0.1° XX ±0.2° SCALE 1:1 SHEET 1/1 UNIT M/M DRAWING DATE Jason_thb 2014/11/25 DESIGN DATE Jason_thb 2014/11/25 CHECK DATE APPROVED DATE JY.W 2014/11/25 3D FILE	深圳市文章济美科技有限公司	
		MICRO RF I BAORD SMT TYPE	
		SERIES MICRO RF SERIES	SIZE A3
		DRAWING NO MICRO-RFB01-C00-00	REV A0

A

B

C

D

E

F

A

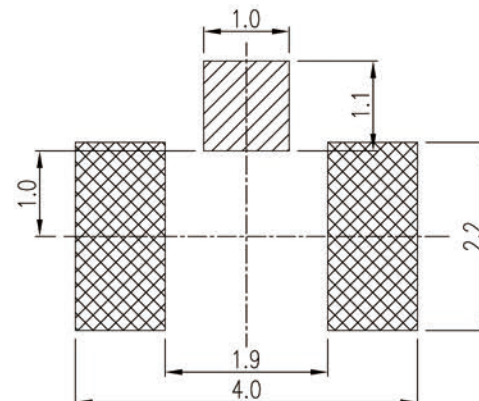
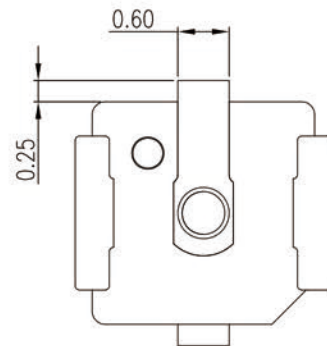
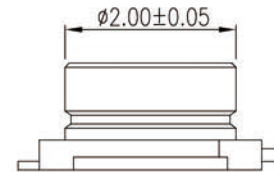
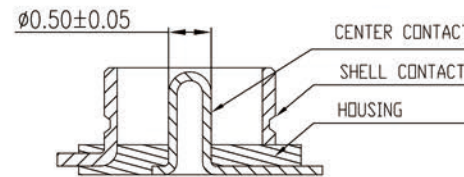
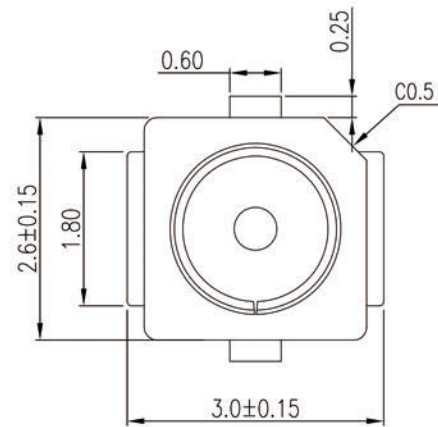
B

C

D

E

F



RECOMMENDED PCB LAYOUT
 (TOLERANCE:±0.05)

CENTER CONTACT
 GROUND CONTACT

PRODUCT SPEC:
 PACKAGE SPEC: